

## 第六章 參考文獻

1. 宋嘉斌，” VCSEL 元件技術發展” ，光學工程，第 70 期，2000 年 6 月。
2. 陳瑞鑫，陳鴻仁，林依恩，” 光通訊原理與技術” ，全華科技圖書，民國 93 年 1 月。
3. 吳文進，朱慕道，” 新型態光通訊模組用封裝技術” ，電子與材料雜誌，第九期，pp. 82-87
4. 鄭木海博士，” 雷射二極體構裝技術之近況與趨勢” ，光訊，第 69 期，1997 年 12 月
5. 蕭忠信，劉如豐，蔡錦益，” 光通訊元件構成設備” ，機械工業雜誌，第 240 期，pp. 222-227
6. 劉信男，” TIG 鍔接實務與電阻點鍔技術” ，全華科技圖書，民國 80 年 11 月。
7. 中國鍔接手冊，第二版，第一卷 鍔接方法及設備，pp. 344-352
8. E. J. DEL VECCHIO, "Resistance Welding Manual" Vol. 1, 3th, pp. 42-52 1956
9. W. h. Kearns, Resistance and Solid-State Welding and Other Joining Processes" Vol. 3, 7<sup>th</sup>, pp. 28-55
10. Kaiser, J. G., Dunn, G. J. and Eagar, T. W., The Effect of Electrical Resistance on Nugget Formation During Spot Welding, Welding Research Supplement, pp. 167-174, 1982.
11. Cho, H. S. and Cho, Y. J., "A Study of Thermal Behavior Resistance Spot Welds", Welding Research Supplement, pp. 236-244, 1989.
12. Khan, J. A., Xu, L. and Chao, Y. J., "Prediction of Nugget Development During Resistance Spot Welding Using Coupled Thermal Electrical Mechanical Model", Science and Technology of Welding Joining, Vol4, pp. 201-207, 1999.
13. Omar, A. A., "Effects of Welding Parameters on Hard Zone Formation at Dissimilar Metal Welds", Welding Research Supplement, pp. 86-93, 1998.
14. Sun, X., "Effect of Projection Height on Projection Collapse and Nugget Formation a Finite Element Study", Welding Journal, pp. 211-216, 2001.
15. Senkara, J., Hang, H. Z. and Hu, S. J., "Expulsion Prediction Resistance Spot Welding", Welding Journal, pp. 123-132, 2004.
16. Ch. Ed. Guillaume, Compt. Rend. Acad. Sci. Paris 170, 1554, 1920.
17. F.Y. Huang, H.M. Chow, S.L. Chen, K.A. Yan, "The machinability of

- KOVAR material”, Journal of Materials Processing Technology, 87, pp. 122-118, 1999.
- 18. ASTM, 1996 Annual book of ASTM standards : section 10 : vol. 10. 04, ASTM, 1996.
  - 19. Arun K. Varshneya “Stresses in Glass-to-Metal Seals”, Treatise on Materials Science and Technology., Vol. 22 Academic Press, New York. pp. 241-306, 1982.
  - 20. Kotaro Honda, Physics and applications of invar alloys, Maruzen company, ltd., Tokyo, 1978.
  - 21. K.J. Ely and Y.Zhou,”Microresistance spot welding of Kovar, Steel, and nickel”,Science and Technology of Welding and Joining , 2001 Vol.6 No.2,pp37-72.
  - 22. M.S. cohen, G.W. Johnson, J.M. Trewella, L.L. Lacey, M.M. Oprysko,”Low-Cost Fabrication of Optical Subassemblies” , Electronic Components and Technology Conference, 1996.
  - 23. D.S. Alles, “Trends in Laser Packaging ”, 40<sup>th</sup> Electronic Components and Technology Conf., vol.1, pp.185-192, May 1991
  - 24. Reith, L.A. et al, “Single-Mode Fiber Packaging for Semiconductor Optical Devices”, IEEE Transaction on Components, Hybrids, and Manufacturing Technology Letters, Vol. 7, No.2(1995), pp.791-797
  - 25. Y.M. Cheung, and C.H. Yiu, “Simulation of the Alignment Sensitivity on the Coupling Efficiency of a Ball-Lens capped TO-Can Laser diode Source into a Single-Mode Fiber”, Int’l Symposium on Electronic Materials and Packaging, 2002, pp197-203